

WHAT IS CLAIMED IS:

1. A conductor pattern comprising:
 - a plurality of straight lines; and
 - a plurality of corners connected to the plurality of straight lines;
 - wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and
 - a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines.
2. A conductor pattern according to Claim 1, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.
3. A conductor pattern according to Claim 1, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.
4. A conductor pattern according to Claim 1, wherein the bottom surface cross-sectional width of each of the

plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

5. A conductor pattern according to Claim 1, wherein the conductor pattern is made of photo-sensitive conductive paste.

6. An electronic component comprising:
a substrate; and
at least one conductor pattern disposed on the substrate, the at least one conductor pattern including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines;

wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and

a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines.

7. An electronic component according to Claim 6, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

8. An electronic component according to Claim 6,
wherein the bottom surface cross-sectional width of each of
the plurality of corners is at least about 1.5 times the
conductor thickness of each of the plurality of corners.

9. An electronic component according to Claim 6,
wherein the bottom surface cross-sectional width of each of
the plurality of straight lines is at least about 0.67 times
the conductor thickness of each of the plurality of straight
lines.

10. An electronic component according to Claim 6,
wherein the conductor pattern is made of photo-sensitive
conductive paste.

11. A method of forming a conductor comprising the
steps of:

forming a photo-sensitive conductive paste on a surface
of a substrate;
exposing the photosensitive conductive paste;
developing the photosensitive conductive paste; and
burning the photo-sensitive conductive paste to produce
a conductor including a plurality of straight lines and a
plurality of corners connected to the plurality of straight

lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines.

12. The method according to claim 11, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

13. The method according to claim 11, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

14. The method according to claim 11, wherein the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

15. The method according to claim 11, wherein the conductor pattern is made of photo-sensitive conductive

paste.

16. A method of forming an electronic component the steps of:

providing a substrate;

forming at least one conductor on the substrate, the step of forming the at least one conductor including the steps of:

forming photo-sensitive conductive paste on a surface of a substrate;

exposing the photosensitive conductive paste;

developing the photosensitive conductive paste; and

burning the photo-sensitive conductive paste to produce a conductor including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines.

17. The method according to claim 16, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the

conductor thickness of each of the plurality of corners.

18. The method according to claim 16, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

19. The method according to claim 16, wherein the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

20. The method according to claim 16, wherein the conductor pattern is made of photo-sensitive conductive paste.